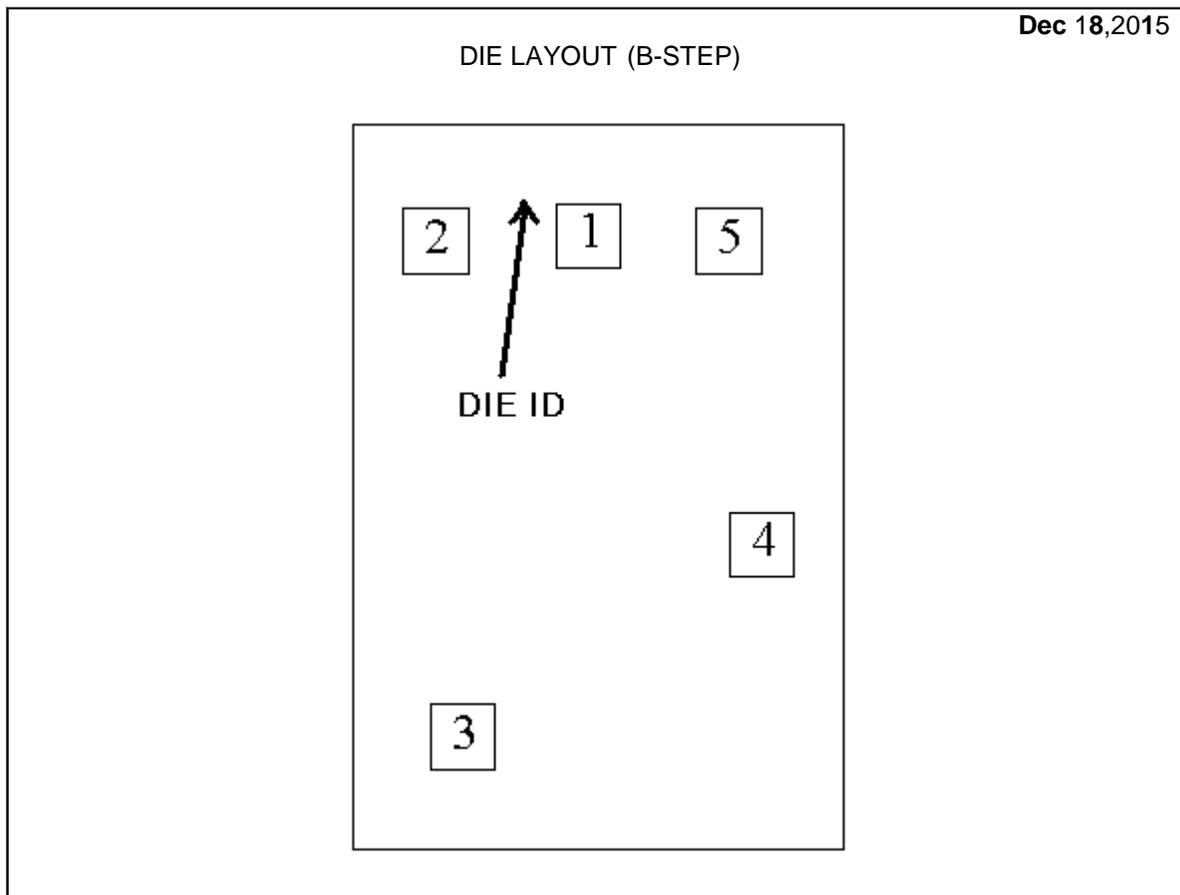


LMH6609-MDC MWC
 900MHZ VOLTAGE FEEDBACK OP AMP

DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6609B	Bond Pad Opening Size (min)	92 μ m x 92 μ m
Die Step	B	Bond Pad Metallization	0.5% COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	PECVD OX+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	699 μ m x 1034 μ m 27.5mils x 40.7mils	Back Side Connection	Floating or -VCC
Thickness	406 μ m Nominal		
Min Pitch	200.41 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT	1	-15	357	92	x	92
V+	2	-232	350	92	x	92
IN-	3	-194	-357	92	x	92
IN+	4	232	-83	92	x	92
V-	5	185	350	92	x	92

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